

Boston March 5, 2007

Workshop: Electrostatic Issues in Semiconductor Manufacturing

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Agenda

- **1:30 – 1:40** **WELCOME AND INTRODUCTION – A. STEINMAN**
- **1:40 – 2:15** **A. STEINMAN (MKS, Ion Systems)**
Overview of Electrostatic Recommendations in Updated E78, E129 and the ITRS 2005
- **2:15 – 3:00** **T. DANGELMAYER – Dangelmayer and Associates**
Perfect ESD Storm – CDM and Class 0 Coverage in Backend Processes
- **3:00 – 3:30** **M. HOGSETT (Novx – MKS, Ion Systems)**
Baseline Data Analysis for Particle Attraction
- **3:30 – 3:45** **QUESTIONS and BREAK**
- **3:45 – 4:15** **T. WELSHER – Dangelmayer and Associates**
Impact of Technology Evolution on Wafer Level ESD Damage
- **4:15 – 4:45** **C.W. LONG – IBM Corporation**
Cleanroom Considerations for ESD Control
- **4:45 – 5:15** **M. NORAS (TREK) – Electrostatic Measurement Issues and SEMI E43**
- **5:15 – 5:30** **ALL - PANEL**

Thoughts for Today

- Physics is the same everywhere. We have no static problems in our factory????
- Denial costs a lot of money.
- As devices become smaller in size, faster in operating speed, and more complex, the static problems will become worse.
- The day we hit a technology barrier in semiconductor production due to static charge is coming closer. HDD and FPD production have already hit this barrier.